



Material Composition Declaration

EPC2214

Company Name	Efficient Power Conversion (EPC)	Issue Date:	4/5/2019
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	3.3 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	2.8651	85.5446	87.7624	855446
	Silicon oxide	7631-86-9	0.0111	0.3323		3323
	Silicon nitride	12033-89-5	0.0035	0.1044		1044
	Gallium nitride	25617-97-4	0.0135	0.4027		4027
	Aluminum	7429-90-5	0.0218	0.6501		6501
	Aluminum nitride	24304-00-5	0.0033	0.0972		972
	Titanium	7440-32-6	0.0005	0.0149		149
	Titanium nitride	25583-20-4	0.0019	0.0573		573
	Copper	7440-50-8	0.0007	0.0216		216
	Tungsten	7440-33-7	0.0008	0.0234		234
	Polyimide		0.0172	0.5138		5138
Under Bump Metal	Titanium	7440-32-6	0.0002	0.0060	0.0660	60
	Copper	7440-50-8	0.0020	0.0600		600
Solder Bump	Tin	7440-31-5	0.3683	10.9970	12.1716	109970
	Silver	7440-22-4	0.0068	0.2016		2016
	Nickel	7440-02-0	0.0122	0.3635		3635
	Copper	7440-50-8	0.0204	0.6094		6094
Sum in total:			3.3493	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.